PSI Roadshow in Q3,2024

Aug. 2024

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- Psi's statements of its current expectations are forward-looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.

- Information as to those factors that could cause actual results to vary can be found in PSI's Annual or Quarterly Report filed with Taiwan Stock Exchange Corporation (TWSE) and such other documents as PSI may file with, or submit to the TWSE from time to time.

- Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

- The numbers of the presentation are prepared under IFRS.

Agenda

- Semiconductor industry trend
- PSI Winning strategies
- Financial performance
- Key takeaways

MSCI Adds PSI To the Global Small Cap Indexes

MSCI TAIWAN INDEX
Additions

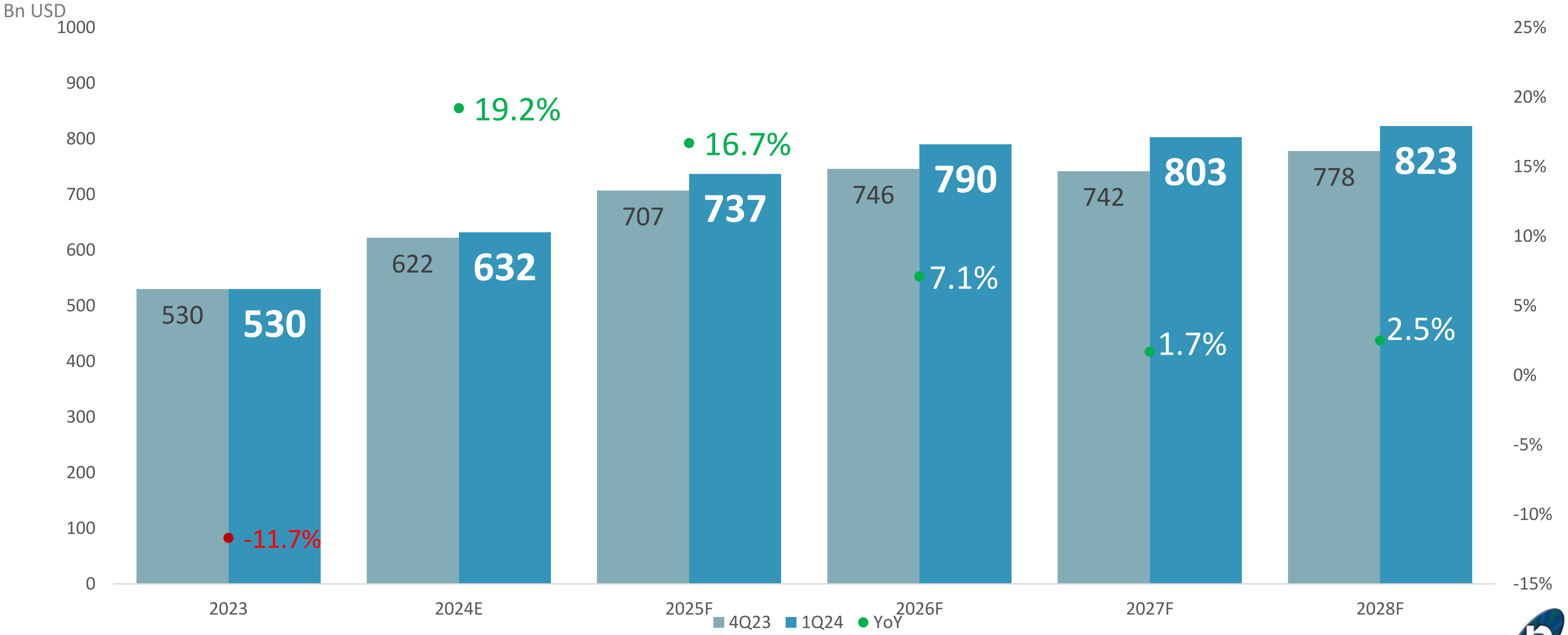
CHENMING ELECTRONIC
ELITE ADVANCED LASER
ERIS TECHNOLOGY
G-SHANK ENTERPRISE CO
HUANG HSIANG CONST
HWANG CHANG GENERAL CONS
JESS-LINK PRODUCTS CO
LUMOSA THERAPEUTICS
PHOENIX SILICON INTERNATIOAL
RDC SEMICONDUCTOR CO
SOLOMON TECHNOLOGY
TYC BROTHER INDUSTRIAL
UNIVERSAL MICROWAVE TECH
YEASHIN INTL DEV

Source: MSCI, 13 Aug 2024

Semiconductor industry trend

Worldwide Semiconductor Revenue FCST

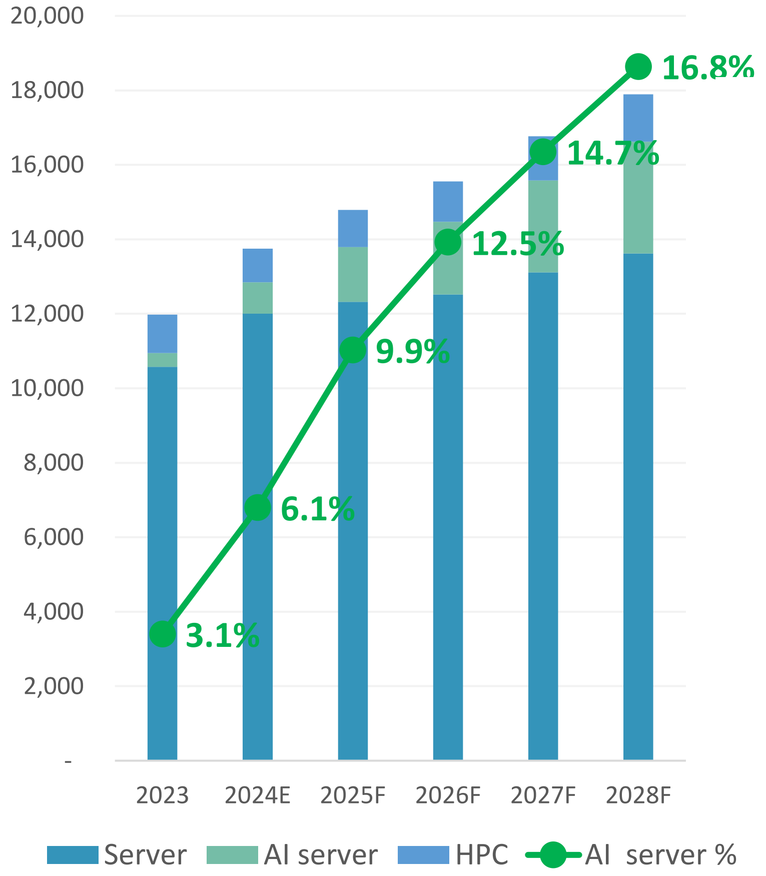
- Double digit growth in 2024 & 2025



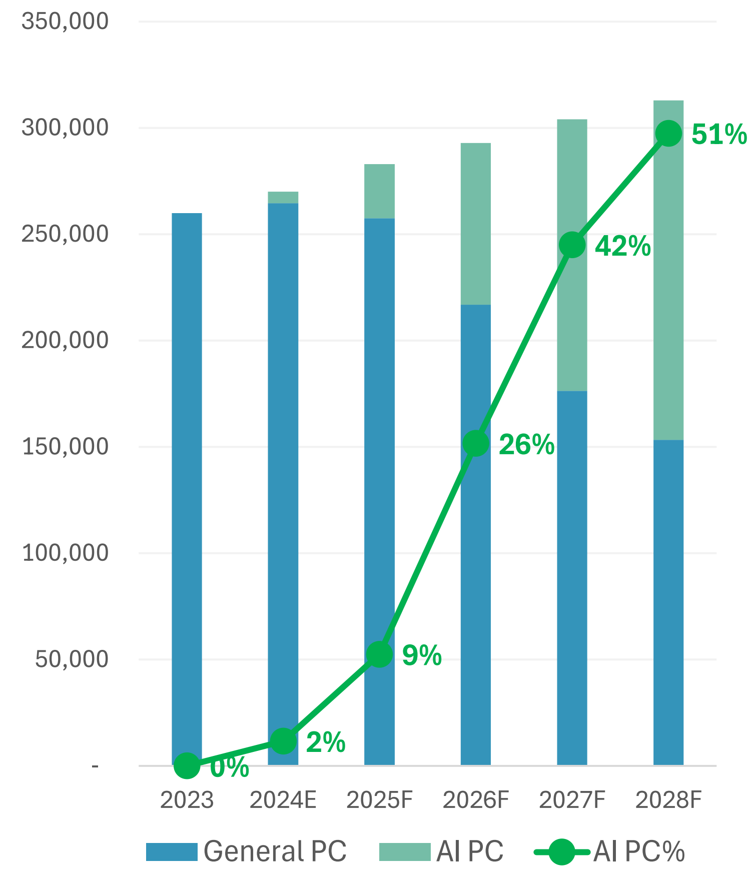
Source: Gartner, Jul. 2024

Semiconductor Mega Trend

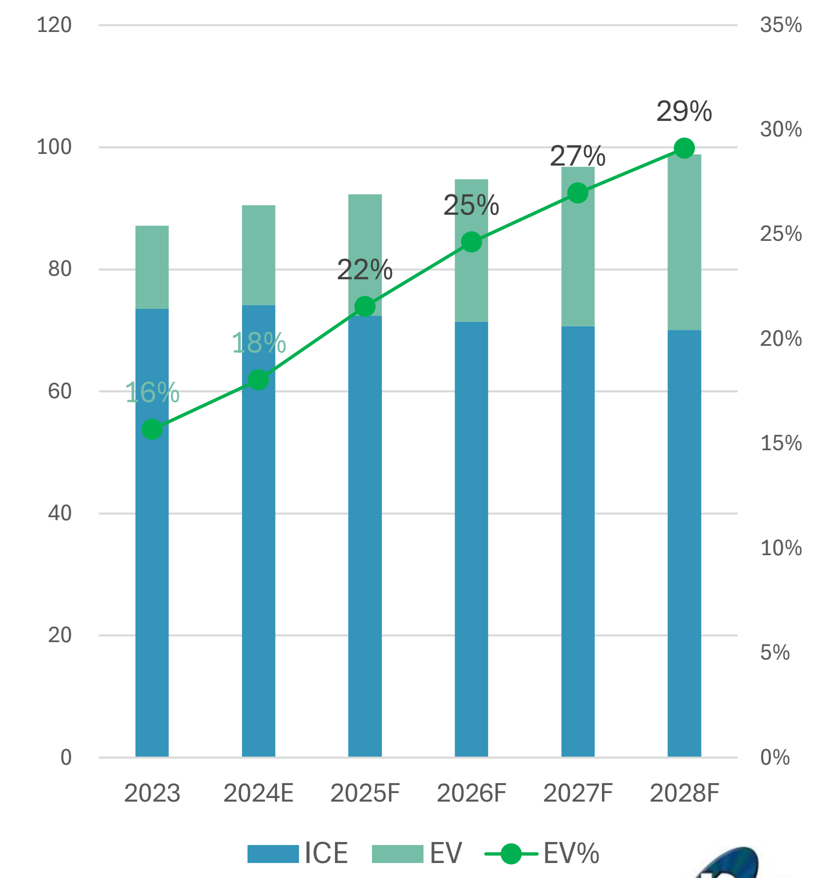
K units **AI server CAGR 53.3%**



K units **AI PC CAGR 133.3%**

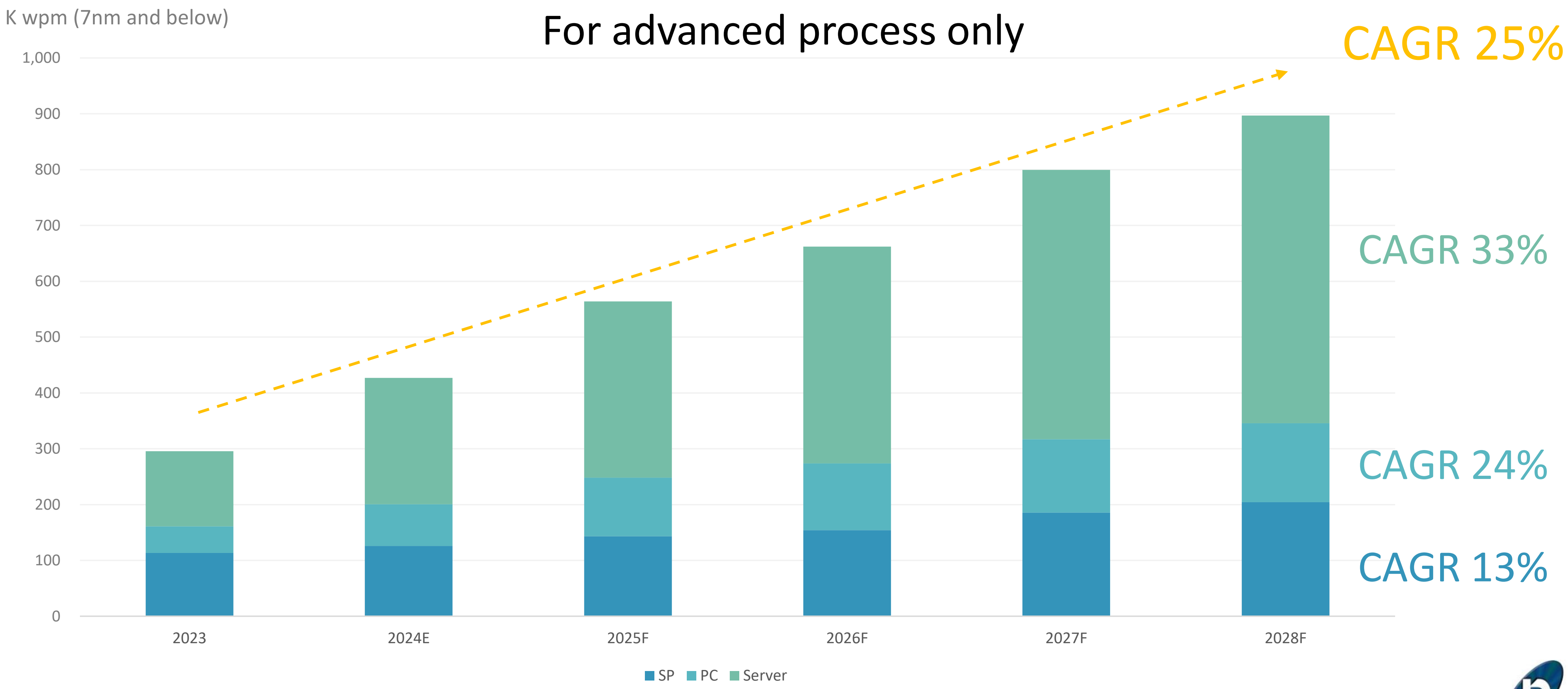


M units **Smart EV CAGR 16.1%**



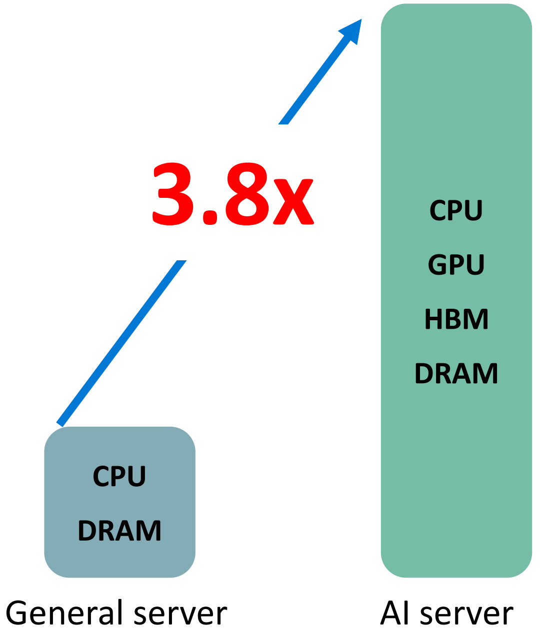
Source: research institution , PSI

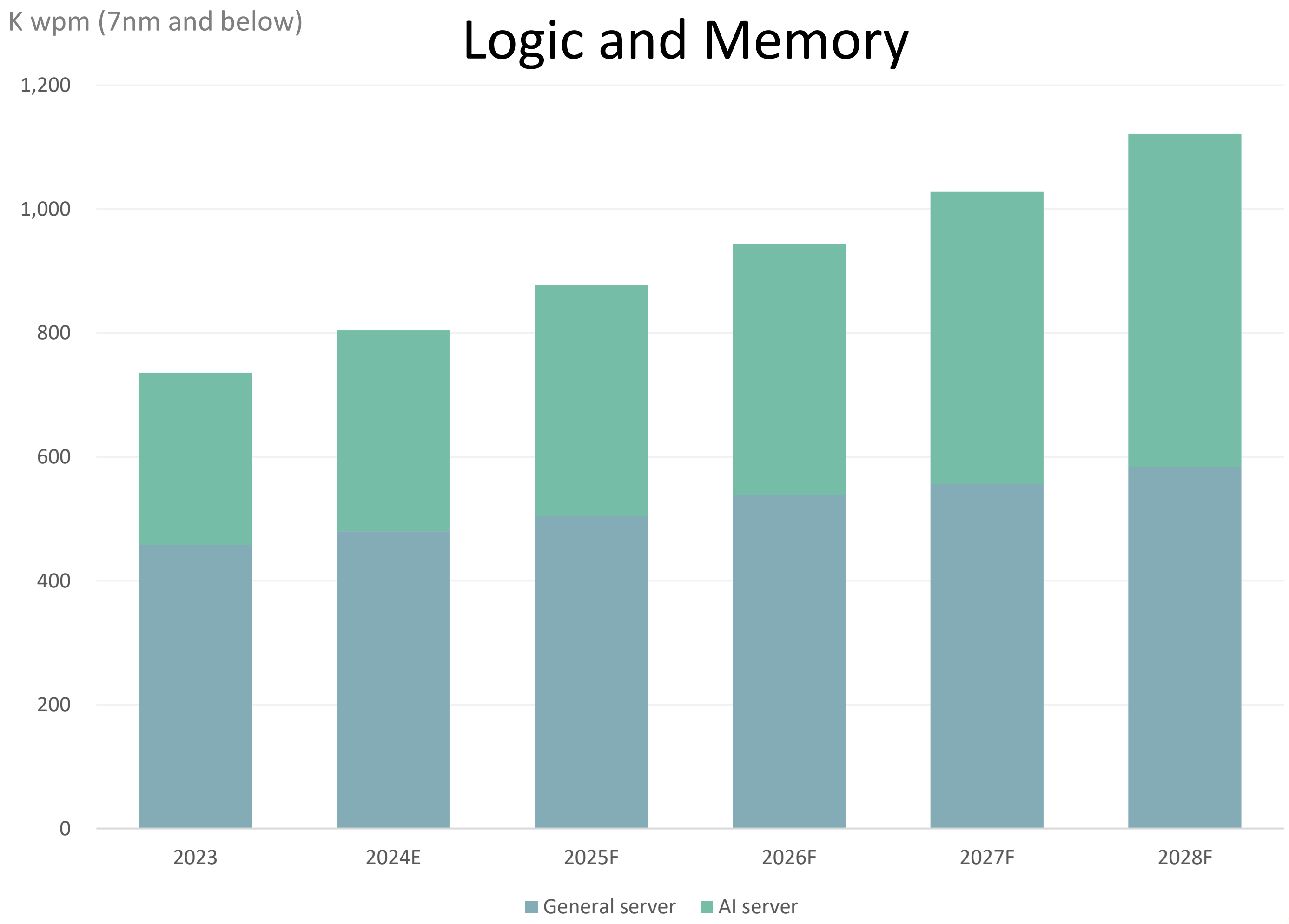
3 Major Applications Require More Wafers



Source: Sumco, May 2024, PSI

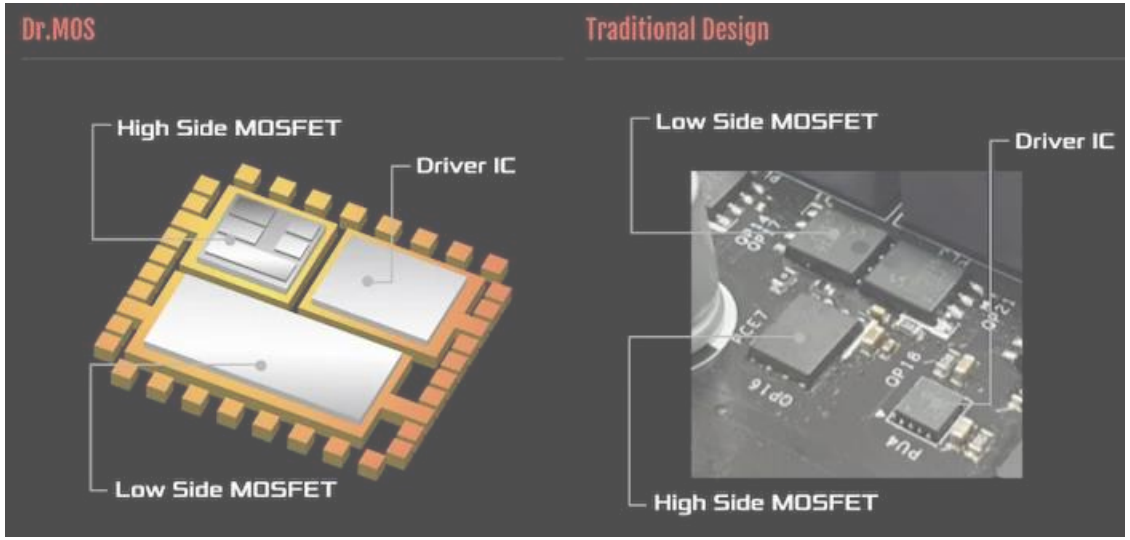
AI Servers Consume 3.8x Leading-edge Wafer



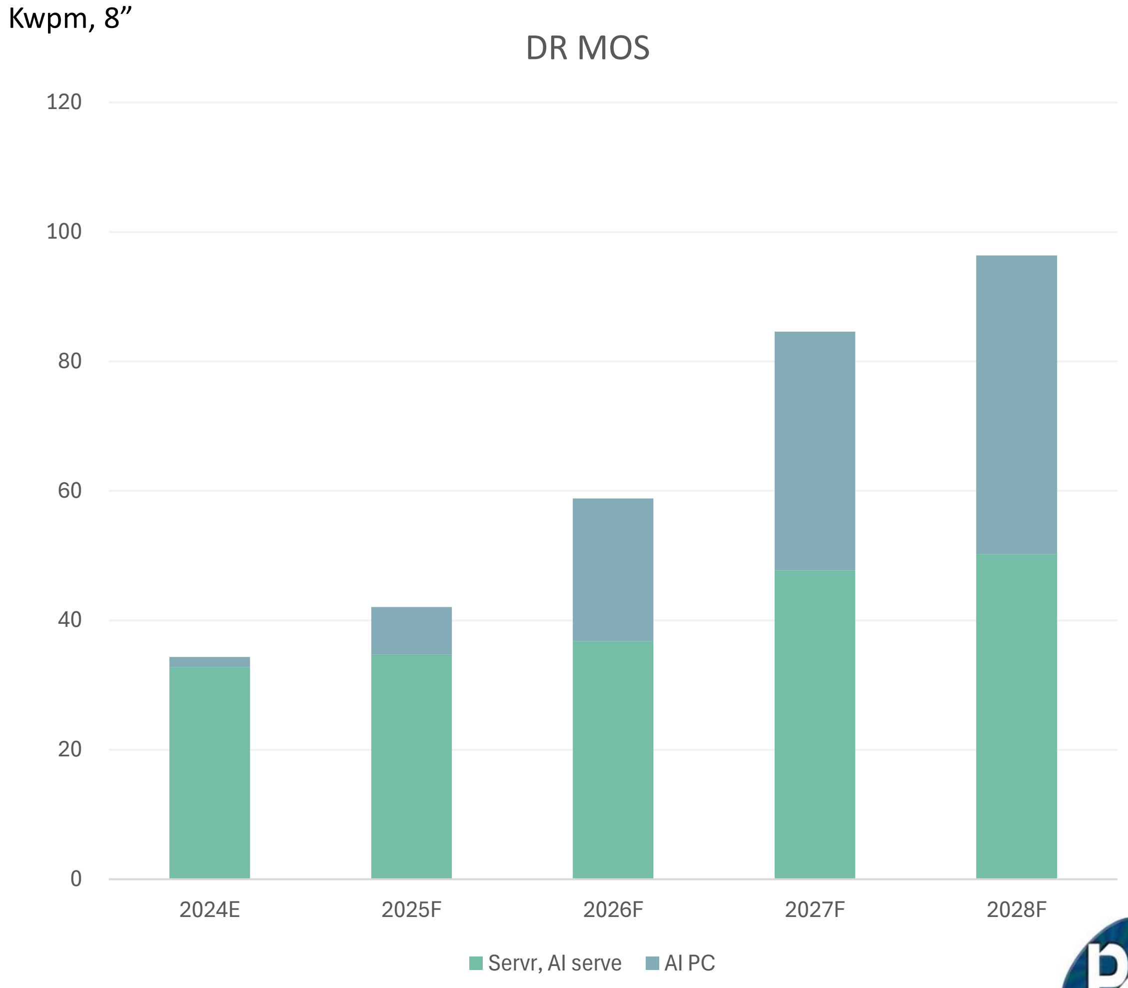


Source: Sumco, May 2024

AI Drive DRMOS Demands On Wafer Thinning



- Providing more stable power to the CPU/GPU
- Miniaturized POWER components and simplified circuits
- **PSI grabs the DRMOS thinning opportunity**



Source: PSI, all about circuit

Wafering 2.0

PSI Business Transformation - Wafering 2.0

Advanced node,

High quality/quantity reclaim

+

Advanced packaging,

Specialized test/carrier wafer

Source: company data

PSI Wafering 2.0 Available Market

High quality/quantity reclaim

Market Size NTD21B in 2027

+

Specialized test/carrier wafer

Market Size NTD14B in 2027

Total SAM NTD35B

PSI Wafering 2.0 Competitive Advantages

Capacity
WW No.1 wafering capacity

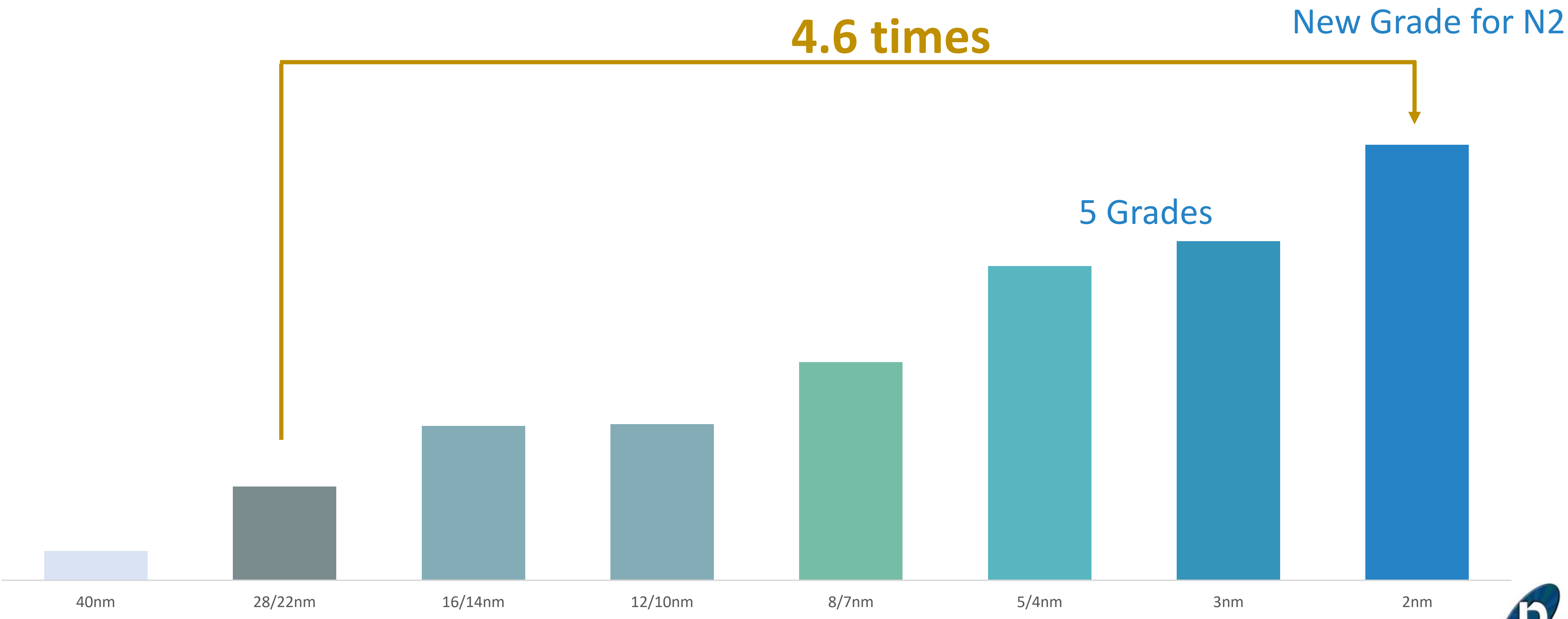
Technology
Leading in Highest-grade reclaim wafer

Fulfilling
Strong partnership with key customer

Efficiency
WW No.1 Lights out Wafering Fab

Benefit Directly from Adv. Node Expansion and UTR

- **PSI 70-75% from Advanced node**
- **PQ both increasing, higher spec reclaimed wafers emerging**



Source: PSI, company data

Specialty Test Wafer And Carrier

- **Multiple applications and specifications, requiring extensive customization**

Test wafer

Monitor & Dummy

Process control

750-810 um

26nm-65nm
(particle size)

Carrier

BSPD, HBM, CIS

Production

767-773 um

<65nm
(particle size)

PSI Wafering **Capacity Pull-in**

510	630	780
2023	~~2025~~ 2024	~~2027~~ 2026

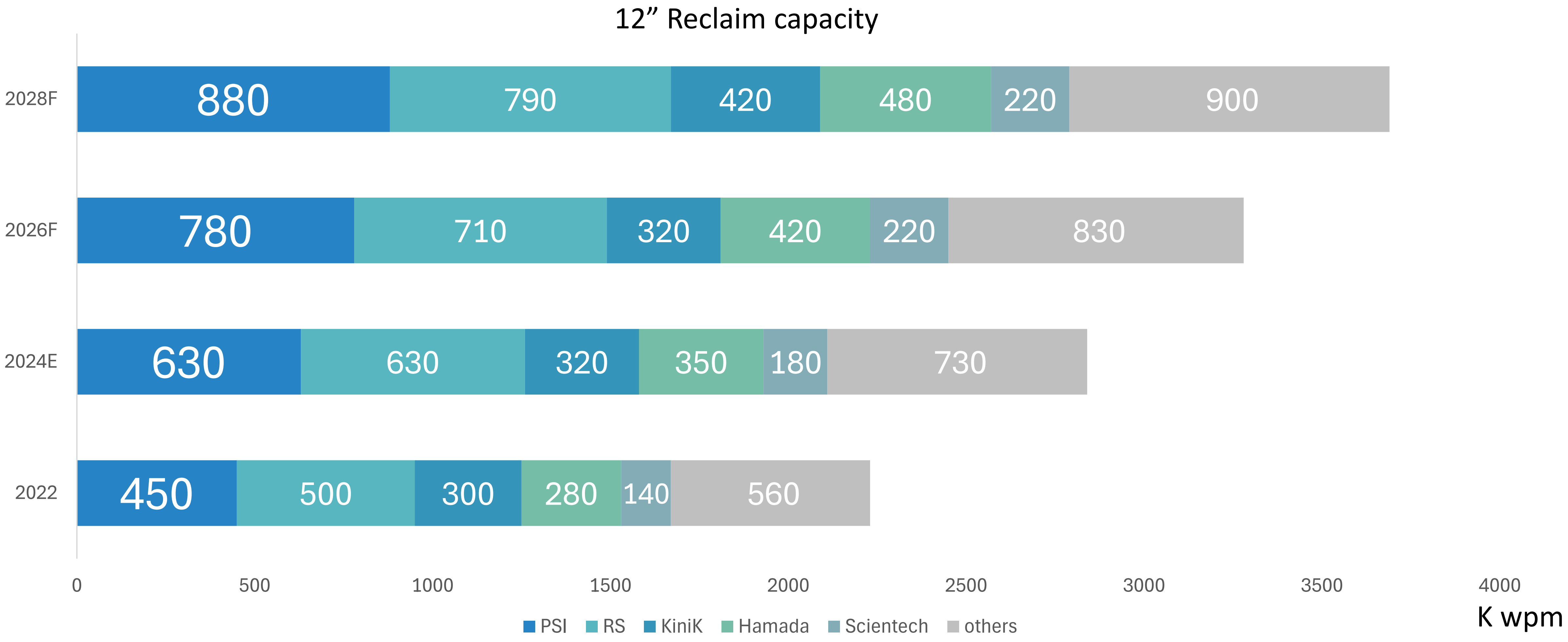
Picture: PSI

WW No.1 **Lights out** Wafering Fab

100	40	15	5
2021	2023	2025	2027

Picture: PSI

Wafering **Capacity WW No.1**



Source: PSI, company data

Thinning 2.0

PSI Thinning 2.0

AI demand driving,

Ultra thin power thinning

+

SiC wafer cost downing,

SiC BGBM foundry thinning

Source: company data

PSI Thinning 2.0 Available Market

Ultra thin power thinning

SAM NTD984M in 2027

+

SiC BGBM foundry thinning

SAM NTD236M in 2027

Total SAM NTD1,220M

Source: company data

PSI Thinning 2.0 Competitive Advantages

WW NO.1 thinning house capacity

Capacity

WW No.1 Taiko MP > 589k Wafer

Technology

Fulfilling

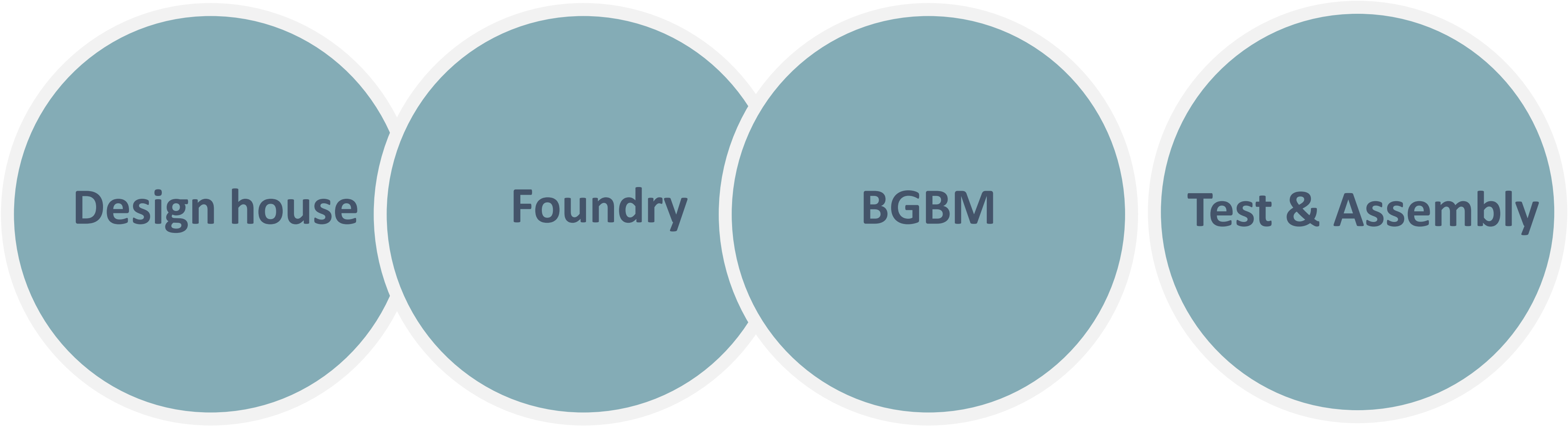
Innovation-Driven Values

Efficiency

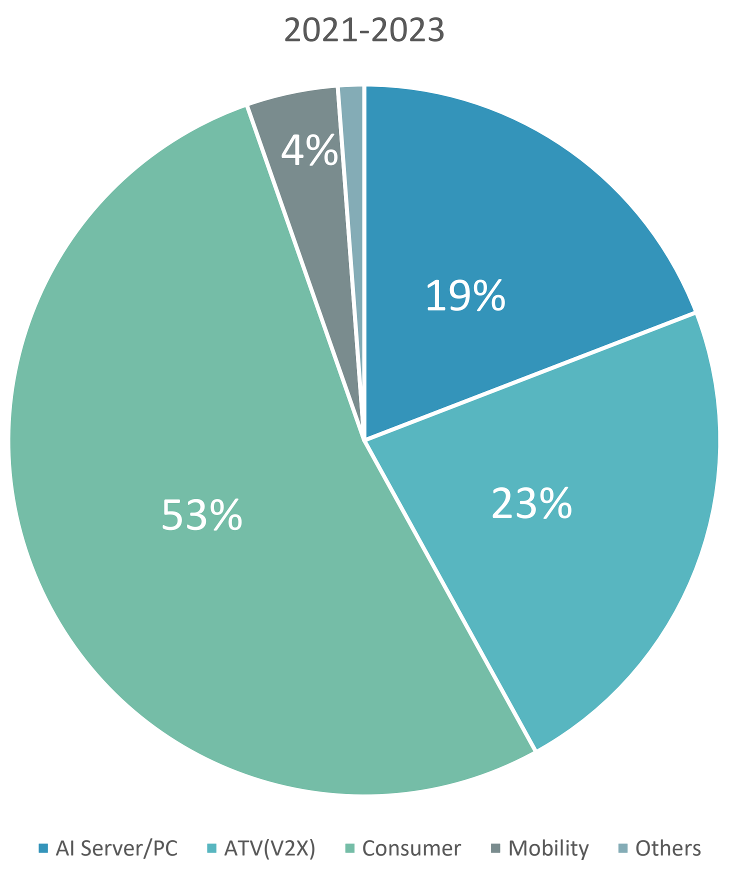
Turnkey solution: FSM – BGBM – Test

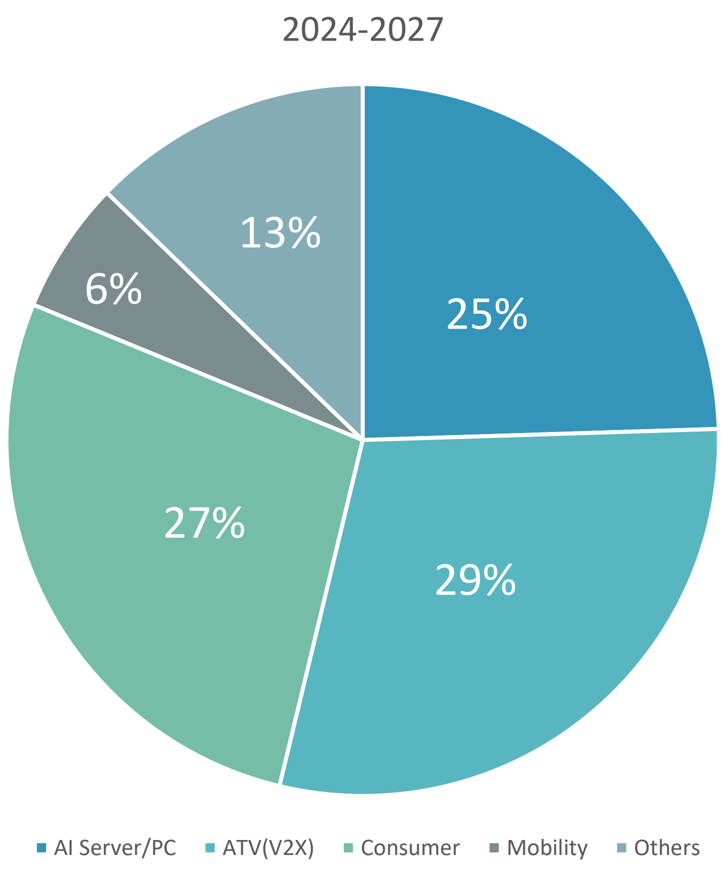
SiC Foundry Ecosystem In Taiwan

- **Require high integration across various processes**
- **SiC virtual IDM is forming in Taiwan**
- **PSI has been proven in SiC BGBM process by customers**



PSI Thinning Strategic Shifting To AI & ATV



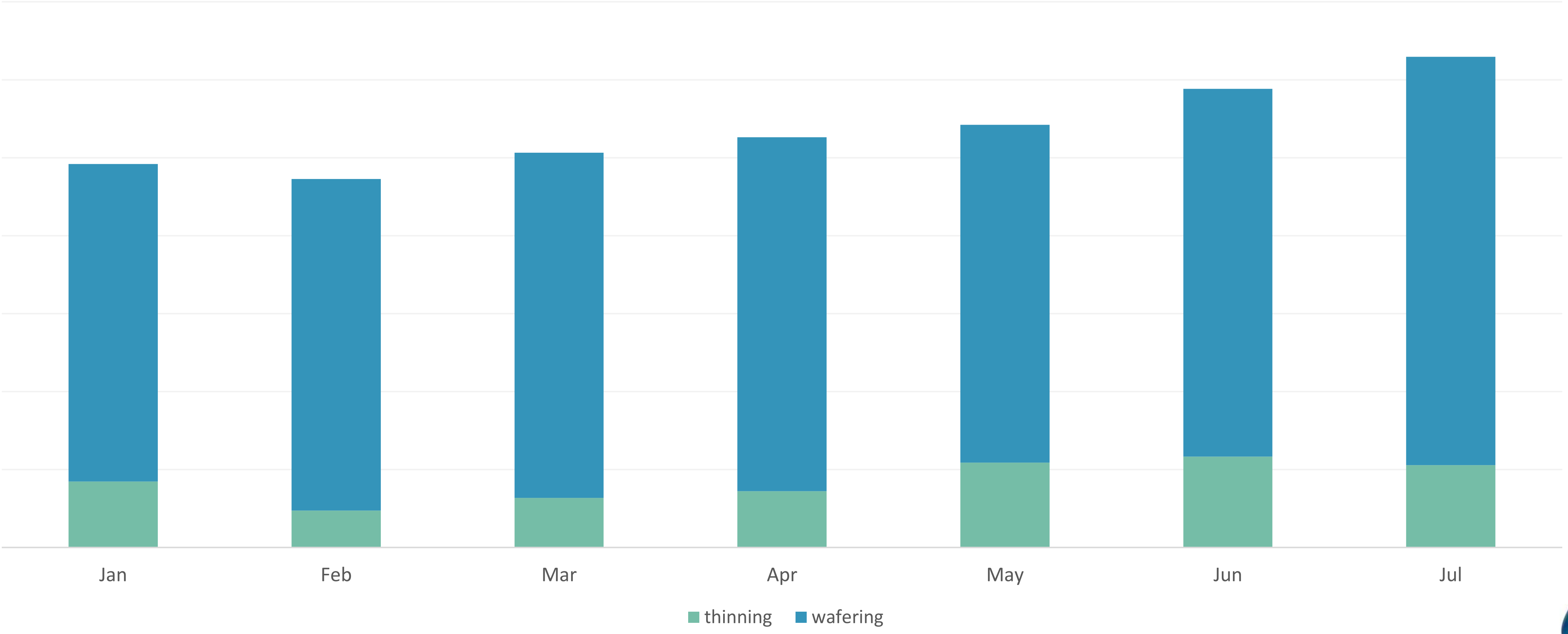


Source: PSI

Financial performance

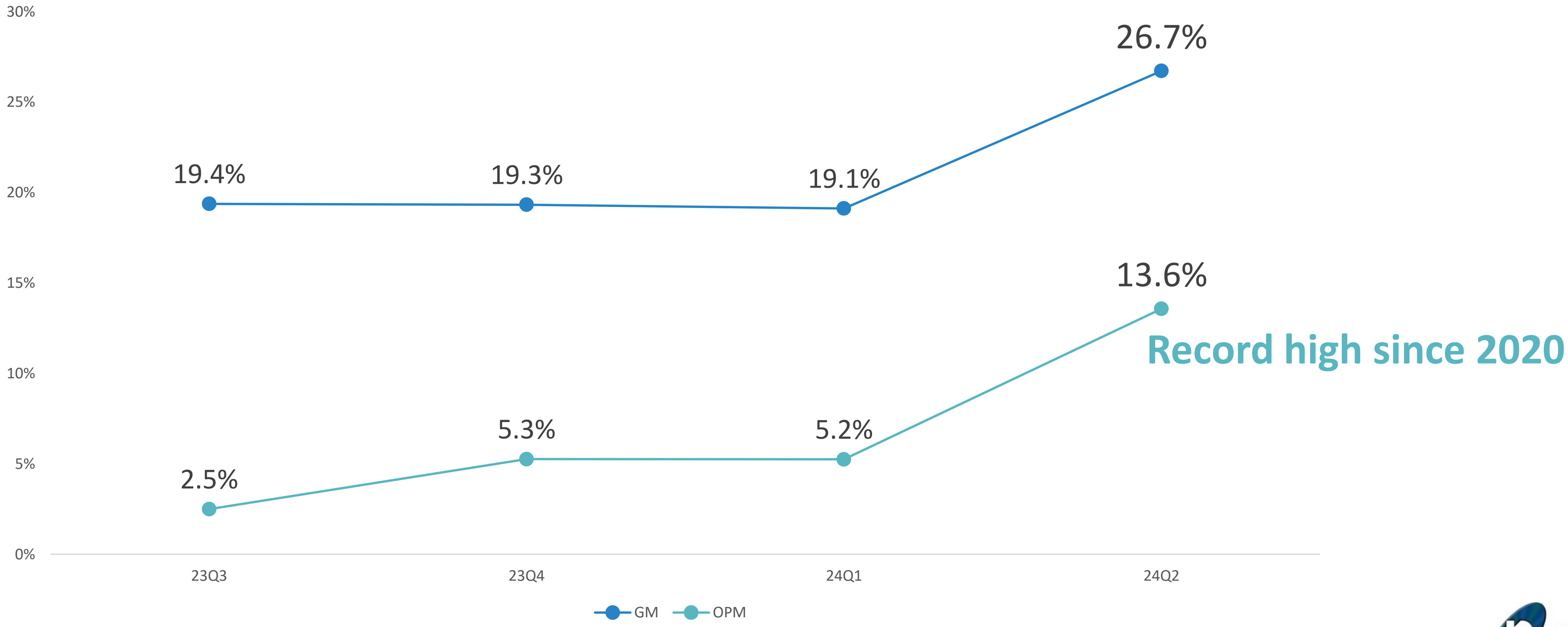
PSI YTD Revenue Trend

- Wafering : Reached a record high revenue in July, continues to drive PSI growth momentum
- Thinning: steady growth



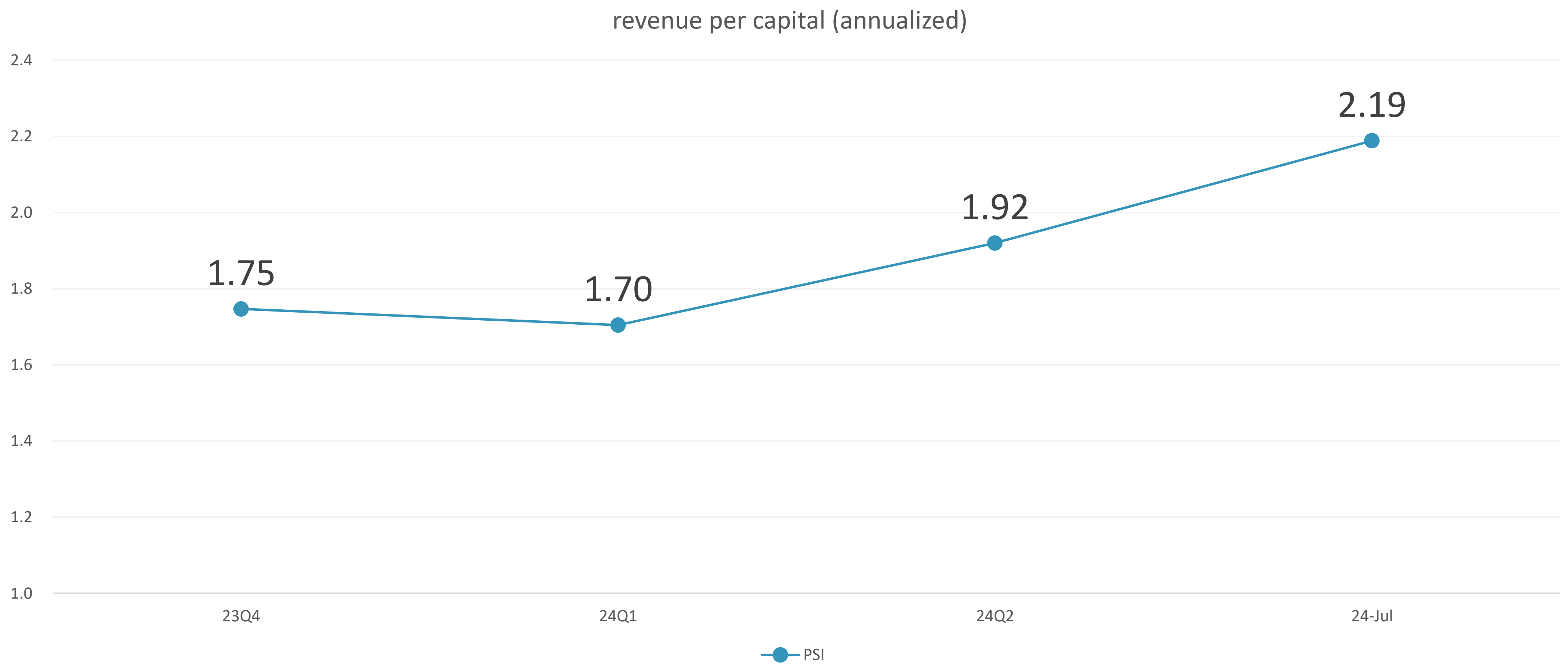
Source: PSI

Gross Margin And Operating Margin Trend



Source: PSI

Capital Efficiency Increasing



Source: PSI

Key Takeaways

- **PSI 2024 marks a transitional year, leading significant growth into 2025**
- **Reclaim business recovers fast for advanced nodes by pulling in Taichung Fab capacity**
- **Wafering 2.0 is shaping to meet new applications in carrier and test**
- **Thinning 2.0 gains momentum from AI Server/PC power management need**
- **PSI 2.0 will boost capital efficiency, enhancing competitiveness and growth**

PSI 2.0